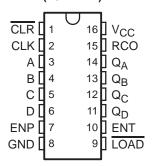
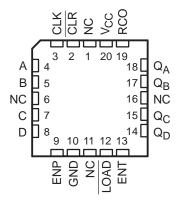
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical  $t_{pd} = 14 \text{ ns}$
- ±4-mA Output Drive at 5 V

SN54HC161...J OR W PACKAGE SN74HC161 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Input Current of 1 µA Max
- Internal Look-Ahead for Fast Counting
- **Carry Output for n-Bit Cascading**
- **Synchronous Counting**
- Synchronously Programmable

SN54HC161 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

## description/ordering information

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. The 'HC161 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

#### ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube of 25	SN74HC161N	SN74HC161N		
		Tube of 40	SN74HC161D			
–40°C to 85°C	SOIC - D	Reel of 2500	SN74HC161DR	HC161		
		Reel of 250	SN74HC161DT			
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC161NSR	HC161		
		Tube of 90	SN74HC161PW			
	TSSOP - PW	TSSOP – PW Reel of 2000 SN74HC161PWR				
		Reel of 250	SN74HC161PWT			
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC161J	SNJ54HC161J		
	CFP – W	Tube of 150	SNJ54HC161W	SNJ54HC161W		
	LCCC – FK	Tube of 55	SNJ54HC161FK	SNJ54HC161FK		

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of



## SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## description/ordering information (continued)

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

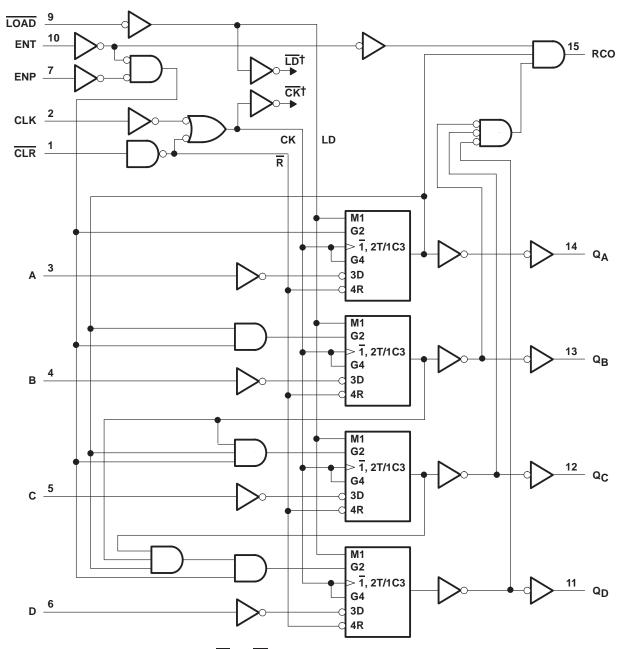
The clear function for the 'HC161 devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.



## logic diagram (positive logic)

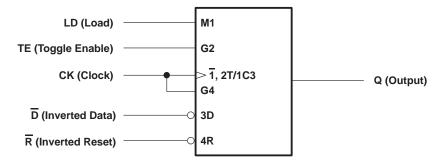


<sup>†</sup> For simplicity, routing of complementary signals  $\overline{LD}$  and  $\overline{CK}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

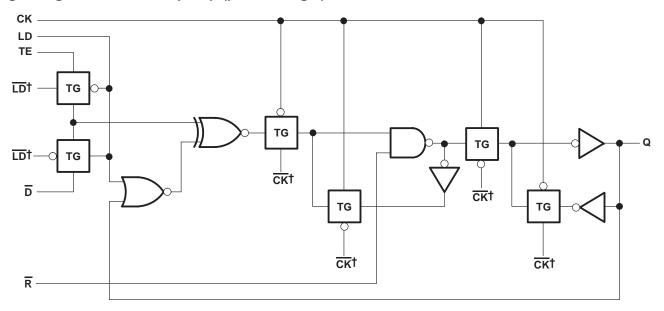
Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## logic symbol, each D/T flip-flop



## logic diagram, each D/T flip-flop (positive logic)

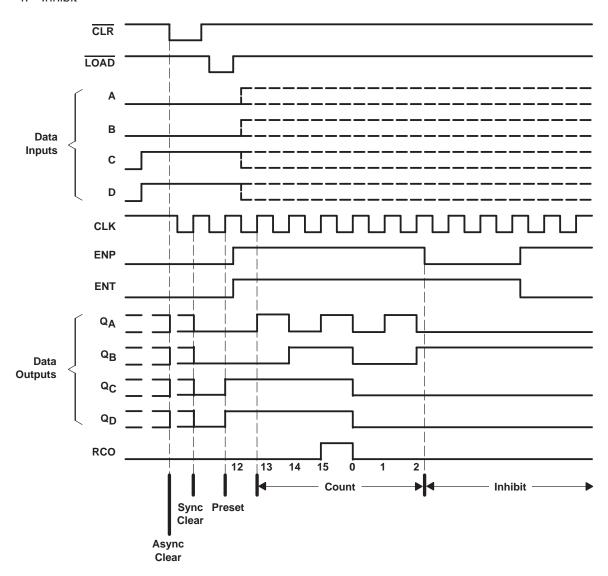


 $<sup>^{\</sup>dagger}$  The origins of  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  are shown in the logic diagram of the overall device.

## typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



## SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>		-0.5	V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	ee Note 1)		±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	c) (see Note 1)		±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	- 		±25 mA
Continuous current through V <sub>CC</sub> or GND			±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2):	: D package		73°C/W
	N package		67°C/W
	NS package		64°C/W
	PW package	1	108°C/W
Storage temperature range, T <sub>sta</sub>		65°C 1	to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			SN	154HC16	61	SI	174HC16	61	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH High-level input voltage		V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V			0.5			0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		V <sub>CC</sub> = 6 V			1.8			1.8	
٧I	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δv‡	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>‡</sup> If this device is used in the threshold region (from V<sub>IL</sub>max = 0.5 V to V<sub>IH</sub>min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t<sub>t</sub> = 1000 ns and V<sub>CC</sub> = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	MOITIONS	.,	Т	A = 25°C	;	SN54H	IC161	SN74H	C161	
PARAMETER	TEST CC	ONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
C <sub>i</sub>		_	2 V to 6 V		3	10	·	10		10	pF

# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			.,	T <sub>A</sub> =	25°C	SN54H	IC161	SN74HC161		
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		
	Pulse duration		6 V	14		20		17		20
t <sub>W</sub>	Pulse duration		2 V	80		120		100		ns
		CLR low	4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	150		225		190		
		A, B, C, or D	4.5 V	30		45		38		
			6 V	26		38		32		
			2 V	135		205		170		
		LOAD low	4.5 V	27		41		34		
	Catura tima a historia CLIKA		6 V	23		35		29		
t <sub>su</sub>	Setup time before CLK↑		2 V	170		255		215		ns
		ENP, ENT	4.5 V	34		51		43		
			6 V	29		43		37		
			2 V	125		190		155		
		CLR inactive	4.5 V	25		38		31		
			6 V	21		32		26		
	•	2 V	0		0		0			
th	t <sub>h</sub> Hold time, all synchronous inputs after CLK↑			0		0		0		ns
				0		0		0		

# SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

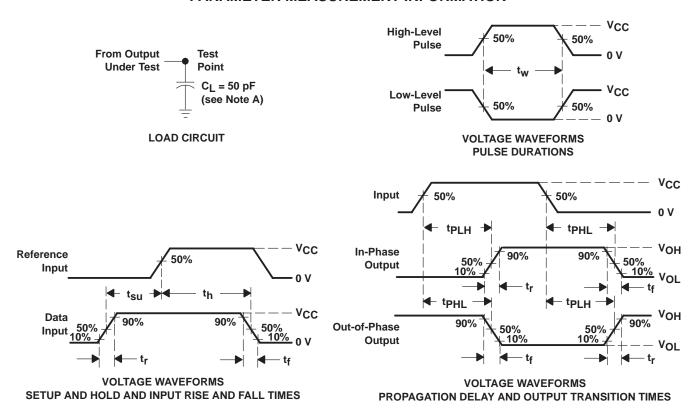
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то		T,	Δ = 25°C	;	SN54F	IC161	SN74F	IC161																
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT															
			2 V	6	14		4.2		5																	
f <sub>max</sub>			4.5 V	31	40		21		25		MHz															
			6 V	36	44		25		29																	
			2 V		83	215		325		270																
		RCO	4.5 V		24	43		65		54																
	CLK		6 V		20	37		55		46																
	CLK		2 V		80	205		310		255																
<sup>t</sup> pd		Any Q	4.5 V		25	41		62		51	ns															
			6 V		21	35		53		43																
			2 V		62	195		295		245																
	ENT	RCO	4.5 V		17	39		59		49																
			6 V		14	33		50		42																
			2 V		105	210		315		265																
		Any Q	4.5 V		21	42		63		53																
t	CLR		6 V		18	36		54		45	ns															
<sup>t</sup> PHL	CLK		2 V		110	220		330		275	115															
		RCO	RCO	RCO	RCO	RCO	RCO	RCO	RCO	RCO	4.5 V		22	44		66		55								
			6 V		19	37		56		47																
		Any	Any	Any	<u> </u>	<u> </u>	Any	Any	Any	Any	Any	Any	Any	Any	Any	Any	Any	2 V		38	75		110		95	
t <sub>t</sub>	tt																	Any	4.5 V							
			6 V		6	13		19		16																

# operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	60	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. For clock inputs,  $f_{\text{max}}$  is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

#### APPLICATION INFORMATION

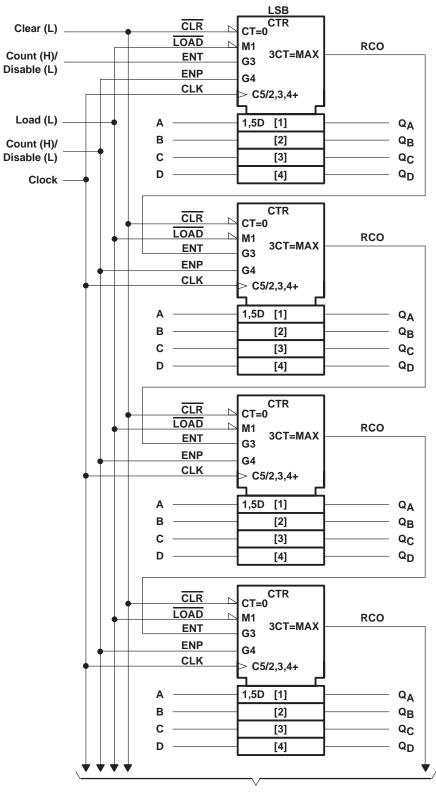
## n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The 'HC161 devices count in binary. Virtually any count mode (modulo-N, N<sub>1</sub>-to-N<sub>2</sub>, N<sub>1</sub>-to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at  $25^{\circ}$ C and  $4.5\text{-V}\ V_{CC}$ ). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).



## **APPLICATION INFORMATION**



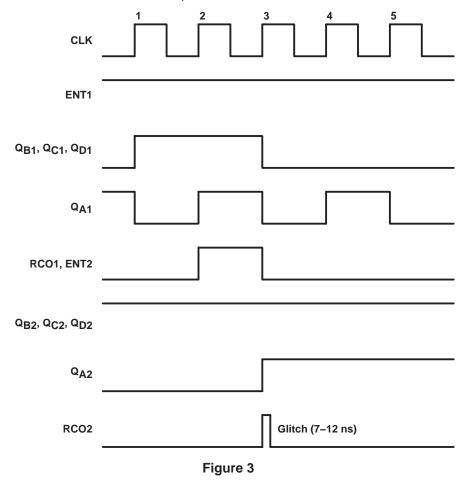
To More-Significant Stages

Figure 2



#### **APPLICATION INFORMATION**

The glitch on RCO is caused because the propagation delay of the rising edge of  $Q_A$  of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT,  $Q_A$ ,  $Q_B$ ,  $Q_C$ , and  $Q_D$  (ENT  $\times$   $Q_A \times Q_B \times Q_C \times Q_D$ ). The resulting glitch is about 7–12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages.  $Q_B$ ,  $Q_C$ , and  $Q_D$  of the first and second stage are at logic one, and  $Q_A$  of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse,  $Q_A$  and RCO of the first stage go high. On the rising edge of the third clock pulse,  $Q_A$  and RCO of the first stage return to a low level, and  $Q_A$  of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.



The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration ( $t_g$ ). In other words,  $t_{max} = 1/(t_{pd} \text{ CLK-to-RCO} + t_g)$ . For example, at 25°C at 4.5-V V<sub>CC</sub>, the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the  $t_{clock}$ ,  $t_{w}$ , and  $t_{max}$  specifications for applications that use more than two 'HC161 devices cascaded together.

#### **APPLICATION INFORMATION**

# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		.,	T <sub>A</sub> = 2	25°C	SN54F	IC161	SN74H	IC161	
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		3.6		2.5		2.9	
f <sub>clock</sub> Clock	ock frequency	4.5 V		18		12		14	MHz
		6 V		21		14		17	
		2 V	140		200		170		
t <sub>W</sub>	Pulse duration, CLK high or low	4.5 V	28		40		36		ns
		6 V	24		36		30		

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Note 4)

	FROM	то	.,	T <sub>A</sub> = 25°C		SN54HC161		SN74HC161		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	3.6		2.5		2.9		
f <sub>max</sub>			4.5 V	18		12		14		MHz
			6 V	21		14		17		

NOTE 4: These limits apply only to applications that use more than two 'HC161 devices cascaded together.

If the 'HC161 devices are used as a single unit, or only two cascaded together, then the maximum clock frequency that the device can use is not limited because of the glitch. In these situations, the device can be operated at the maximum specifications.

A glitch can appear on RCO of a single 'HC161 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input except an ENT of another cascaded 'HC161 device must take this into consideration.

www.ti.com

14-Aug-2021

## **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	<b>Device Marking</b> (4/5)	Samples
5962-8407501VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8407501VE A SNV54HC161J	Samples
84075012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84075012A SNJ54HC 161FK	Samples
8407501EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8407501EA SNJ54HC161J	Samples
8407501FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8407501FA SNJ54HC161W	Samples
JM38510/66302BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 66302BEA	Samples
M38510/66302BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 66302BEA	Samples
SN54HC161J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC161J	Samples
SN74HC161D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161DG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161DT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC161N	Samples
SN74HC161NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC161N	Samples
SN74HC161NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SN74HC161PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples

www.ti.com 14-Aug-2021

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC161PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC161	Samples
SNJ54HC161FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84075012A SNJ54HC 161FK	Samples
SNJ54HC161J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8407501EA SNJ54HC161J	Samples
SNJ54HC161W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8407501FA SNJ54HC161W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

## **PACKAGE OPTION ADDENDUM**

www.ti.com 14-Aug-2021

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54HC161, SN54HC161-SP, SN74HC161:

Catalog: SN74HC161, SN54HC161

Military: SN54HC161

• Space : SN54HC161-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

## TAPE AND REEL INFORMATION





A0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All ulmensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC161DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC161NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC161PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC161PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC161DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC161NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74HC161PWR	TSSOP	PW	16	2000	853.0	449.0	35.0
SN74HC161PWT	TSSOP	PW	16	250	853.0	449.0	35.0

## PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

## **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
84075012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74HC161D	D	SOIC	16	40	507	8	3940	4.32
SN74HC161DG4	D	SOIC	16	40	507	8	3940	4.32
SN74HC161N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC161N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC161NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC161NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC161PW	PW	TSSOP	16	90	530	10.2	3600	3.5
SNJ54HC161FK	FK	LCCC	20	1	506.98	12.06	2030	NA

# FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# D (R-PDS0-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## **IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated